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## Erratum

## Erratum to “Physical mechanisms of heat transfer during single bubble nucleate boiling of FC-72 under saturation conditions-II: Theoretical analysis” [Int. J. Heat Mass Transfer 52 (2009) 1295–1303]

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The publisher regrets that errors arose on pages 1299 and 1302 of this article.

Page 1299, column 2, paragraph following Eq. (15) should read as follows:

Eq. (15) is only valid until the surface is completely rewetted by the liquid front. But, as can be seen in Fig. 4, heat transfer continues long after the liquid front passes over a sensor. So, an expression for heat flux should be developed after the contact line reaches  $r_2$  at  $t_r = (r_1 - r_2)/v$ . This was achieved by integrating the governing equation for heat flux at an arbitrary point  $r''$  that has been in contact with liquid for  $t - t'' = t - (r_1 - r'')/v$ .

Page 1302, column 1, lines 12–18 should read as follows:

2. The activation time period of the microlayer evaporation mechanism is about half of  $t_g$ . Transient conduction heat transfer mainly takes place during the second half of  $t_g$ , when the contact line advances and liquid rewets the contact area. This mode of heat transfer lasts for only a few milliseconds and diminishes on most of the surface before the bubble departure.

The publisher apologizes for any inconvenience.

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